





# Development and Validation of a Simulation Tool to Predict the Combined Structural, Electrical, Electrochemical, and Thermal Responses of Automotive Batteries

Principal Investigator – Chulheung Bae Ford Motor Company

2017 DOE Vehicle Technologies Office Annual Merit Review and Peer Evaluation Meeting Jun 6, 2017

Project ID - ES296





#### **Timeline**

- Start: Jan 1, 2016.
- End: Dec 31, 2018.
- Percent completion: 42%.

#### **Barriers Addressed**

- Battery/Energy Storage R&D
  - Cost.
  - Abuse tolerance.
    - Robust to the safety requirements.

#### **Budget**

- Total contract value: \$4.375M
  - \$3.5M DOE/TARDEC share
  - \$875k Ford share
- Funding received in 2016: \$695k (EERE)
- Funding for FY 2017: \$1.187M (EERE)

#### **Subcontracts**

- Project lead: Ford Motor Company.
- Subcontractor: Oak Ridge National Laboratory (ORNL).





 Project objective: Develop a simulation tool to predict the combined structural, electrical, electrochemical, and thermal (EET) responses of automotive batteries to crash-induced crush and short circuit, overcharge, and thermal ramp and validate it for conditions relevant to automotive crash.

#### Impact:

- Cost.
  - Cost reduction by shortening development cycle and optimizing crash protection systems.
- Abuse tolerance performance.
  - Improvement in abuse tolerance by delivering a predictive simulation tool to shorten or eliminate design – build – test prototype cycles and accelerating development and optimization of crash protection systems robust to the safety requirements.

### **Milestones**



	20	16			20	17	
Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
							4
	Q1		2016 Q1 Q2 Q3				

#### **Project Plan** EET Coupling Crush Crush with Mechanics (Pack) Contact Mechanical Resistance **Parameters** Electrical/Thermal External Equations Parameters of State **Outside Normal** Overcharge Operation Mesh Electrical & Thermal Performance **Parameters** EM & Thermal Solver Updates Input Parameter Simulation Development

Not started

On-track

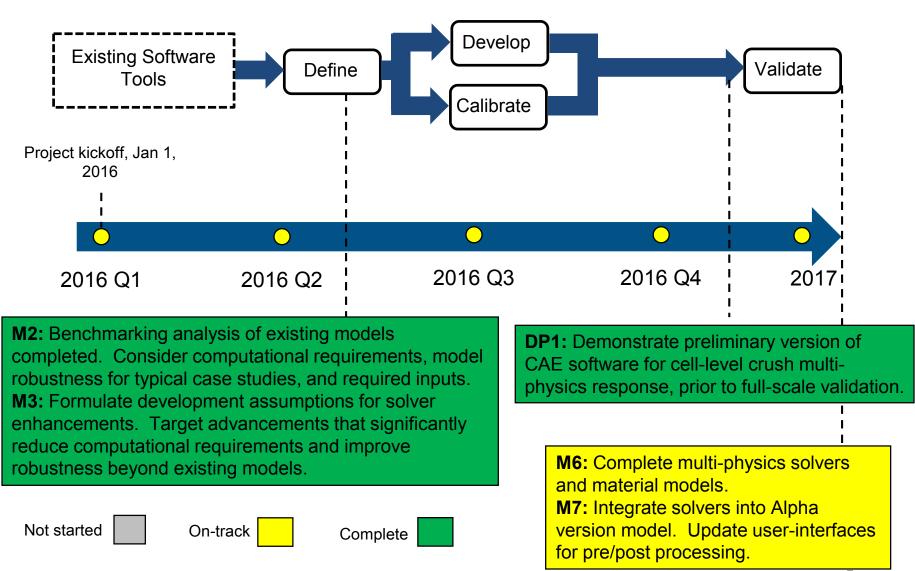
Complete



### Ford

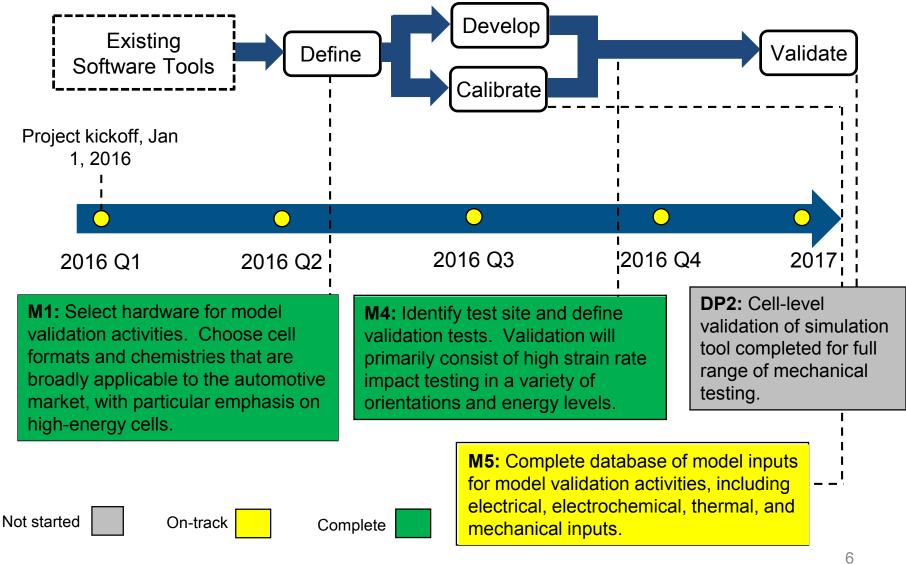
### Approach – Model Development





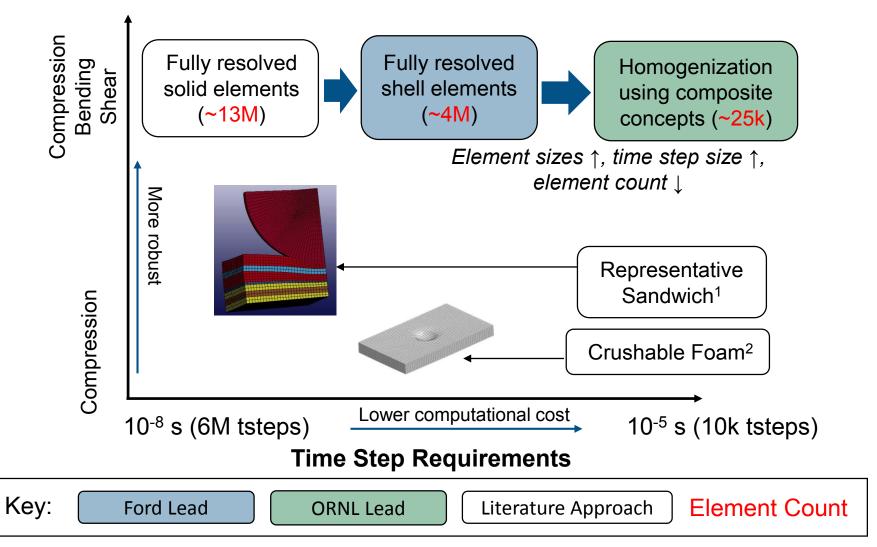
### Approach – Model Validation





### Approach – Targeted Development

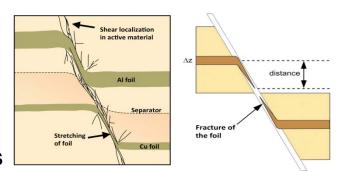




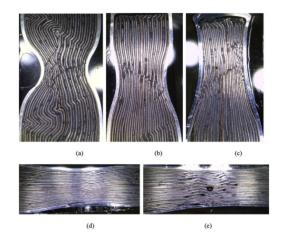
### Technical Accomplishments and Progress: Development of Layered Solid Model (ORNL)



- Failure mechanism.
  - Initial homogeneous compression of the J/R.
  - Increased loading exceeds the strength of the J/R resulting in a localized fault formation.
  - Materials flow and internal rearrangement.
  - Separator failure leading to internal short circuit as opposite electrode materials come into contact.



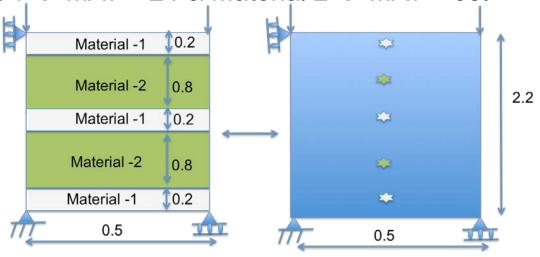
- Approach for modeling of cell deformation (Layered solid).
  - Avoid modeling of every layer and interface with separate finite elements.
  - Multiple layers in a single finite element allow for modeling of cooperative faults, interfacial faults, between the layers, while scaling up the cell response.
  - Faster than solid element model.



# Technical Accomplishments and Progress: Development of Layered Solid Model –Through Thickness Compression

- The objective is to have response of the solid element assembly be the same as for the single layered element with integration points located in the corresponding layer locations.
- Employed is commonly used material models for electrode materials.
- Crushable Foam (MAT-63) and Elasto-Plasticity (MAT-24) for current collector and separator.

Material 1 → MAT – 24 & Material 2 → MAT – 63.



1 solid element for each material

#### Fully Resolved (1 solid element for each material)

- # elements = 5
- Minimum element thickness = 0.2

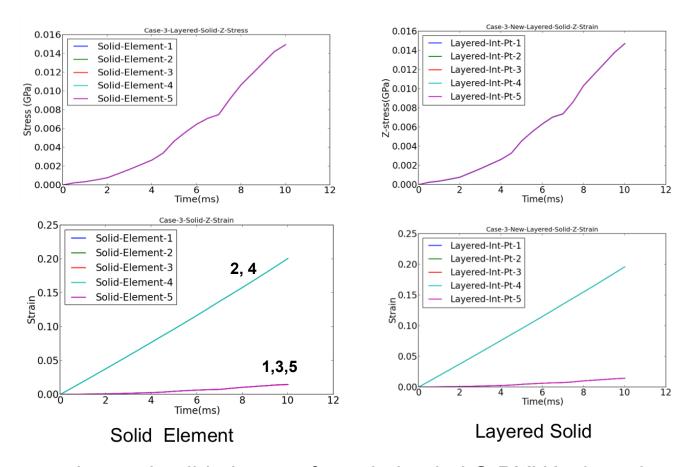
#### Layered Solid

• # elements = 1

Layered Solid

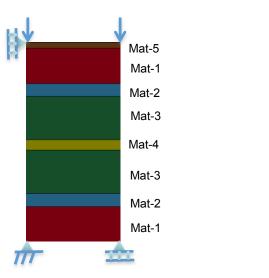
Minimum element thickness = 2.2

# Technical Accomplishments and Progress: Layered Solid Riber Model –Through Thickness Compression Simulation Results



- The new layered solid element formulation in LS-DYNA gives the same response as the assembly of solid elements.
- The new layered solid element formulation reduces the number of degrees of freedom, computational time, and account for the cell inhomogeneity.

# Technical Accomplishments and Progress: Layered Solid Riber Model – Multi Material Configuration Test



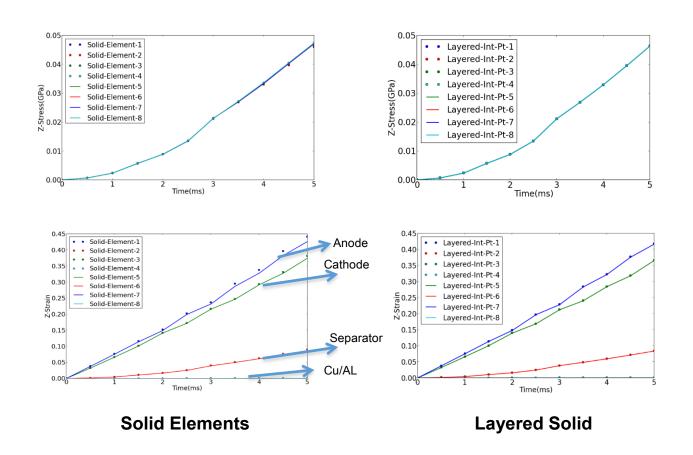
Solid element assembly

Layered solid element

Component	Material	Material Model	Thickness (mm)	Elastic Modulus (GPa)
Anode	Mat-1	Mat-63	0.065	0.465
Separator	Mat-2	Mat-24	0.024	0.5
Cathode	Mat-3	Mat-63	0.080	0.55
Aluminum	Mat-4	Mat-24	0.019	70
Copper	Mat-5	Mat-24	0.011	110

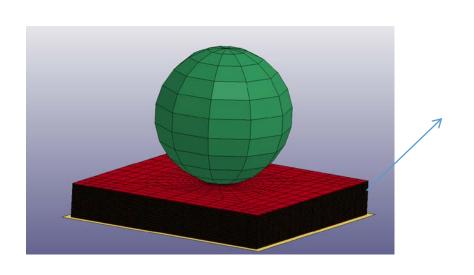
- Test of new formation for material properties are characteristic of a cell J/R.
- Notice large contrast in properties of different layers.
- In assemblies of solid elements without constraints, such contrast would lead to large numerical instabilities.

# Technical Accomplishments and Progress: Layered Solid Riber Model – Multi Material Configuration Test Results

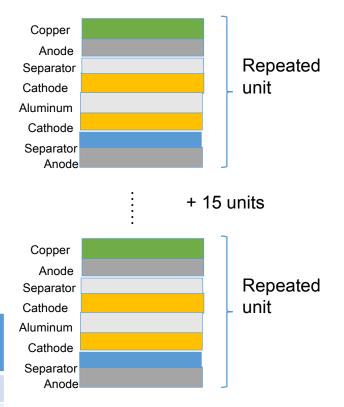


- Responses are the same even for large contrasts in material types and properties.
- One layered element replaces 8 solid elements.

# Technical Accomplishments and Progress: Layered Solid Riber Model – Cell Indentation\_Solid Elements



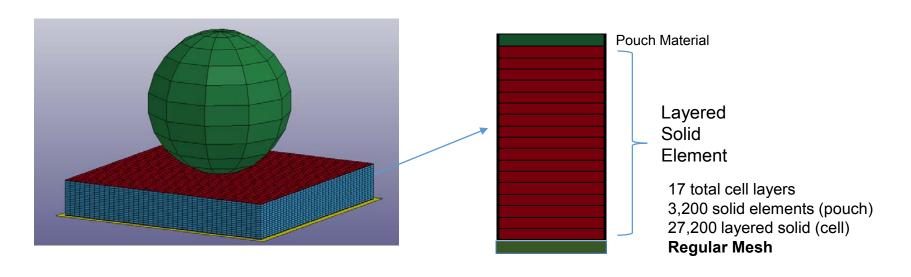
Component	Thickness (mm)	Material Model	Elastic Modulus (GPa)	Yield Strength (GPa)
Copper	0.011	MAT-24	110	0.24
Anode	0.064	MAT-24	0.45	0.04
Separator	0.024	MAT-24	0.5	0.06
Cathode	0.080	MAT-24	0.55	0.04
Aluminum	0.018	MAT-24	70	0.24



2 pouch layers at the top and bottom 17 total cell layers 556 elements per layer 76,728 solid elements

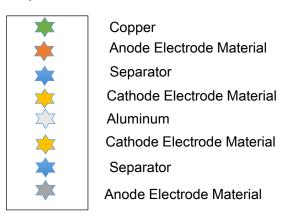
Gradient mesh was necessary to control the size of the model.

# Technical Accomplishments and Progress: Layered Solid Riber Model – Cell Indentation\_Layered Solid Elements

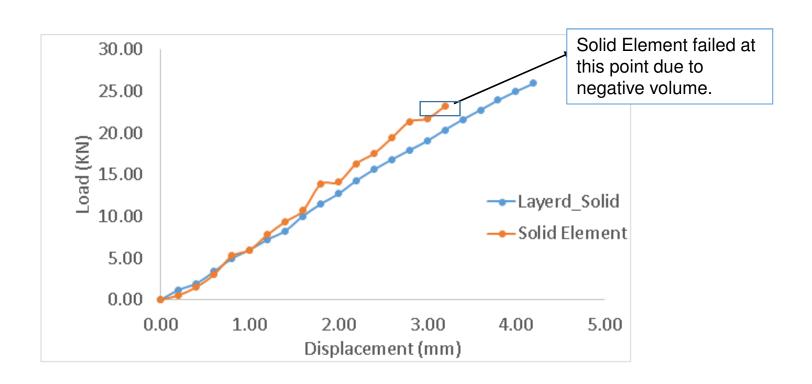


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#### Layered Element



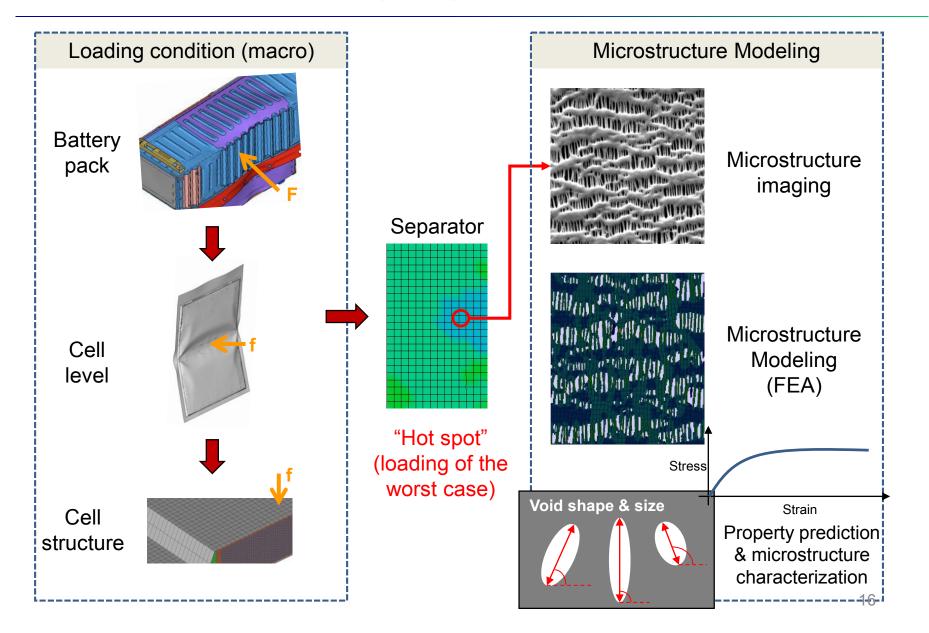
# Technical Accomplishments and Progress: Layered Solid Riber Model – Indentation Simulation Comparison



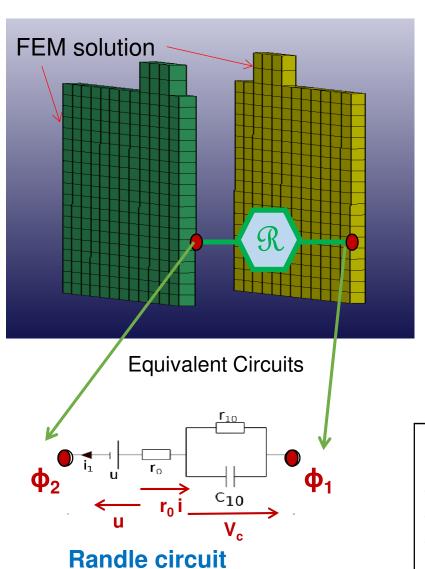
- Solid element CPU time = 52,705 sec.
- Layered solid element CPU Time = 2,248 sec.
- New layered element formulation is 22.8 times faster while having 2.52 times fewer elements.

# Technical Accomplishments and Progress: Microstructure Model (Ford)

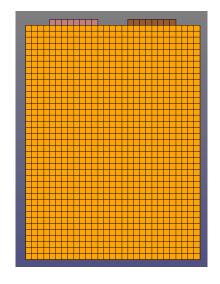


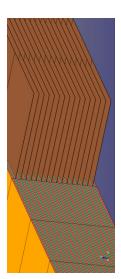


# Technical Accomplishments and Progress: LS-DYNA EM Resistive Solver & Electrical Model Development Progress



#### **Current Mesh Implementation**





- 5 mm edge length
- ~150k elements per cell
- 1 element per component thickness

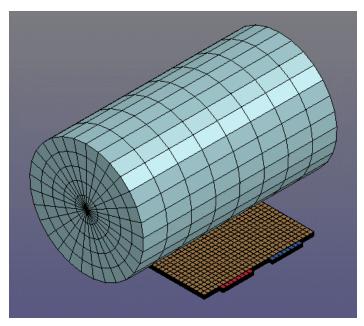
#### Model Inputs

- Bulk heat capacity and thermal conductivity
- Cell-level calibration of circuit parameters
- Type A cell (15 Ah pouch, Graphite & NMC/LMO)

### Technical Accomplishments and Progress: Internal Short Model – Cell Crush Model Set Up







**Experimental Setup** 



**Target Time Steps** 

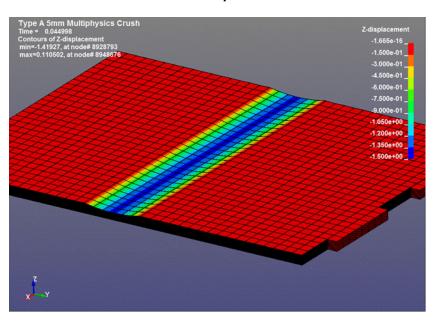
Crash (Vz = 5 m/s) Mech + Electrical + Thermal tf = 0.2 ms; dt = 0.2 μs "Freeze" mechanics

Electrical + Thermal tf = 50 s; dt = 1 s

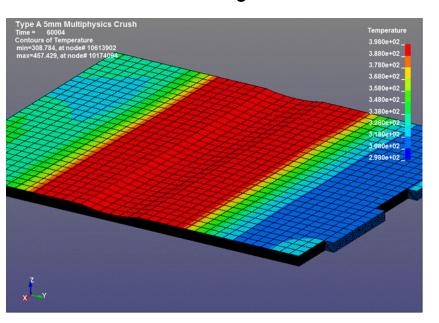
# Technical Accomplishments and Progress: Crush Coupling with Multi-Physics Solvers



#### Nodal Z-Displacement



#### Thermal Fringe Plots



- Coupling with multiphysics using deformable to rigid switch for "crash" case study and newly developed LS-DYNA keyword \*EM\_RANDLE\_SHORT.
- Assuming compressive strain causes onset of short circuit.
- Future work will focus on accuracy and robustness improvements, and integration with ORNL layered solid models.

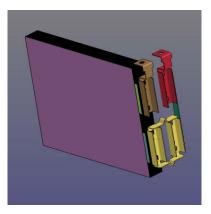
### Technical Accomplishments and Progress: External Short Model



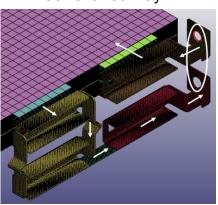
**Test Hardware** 



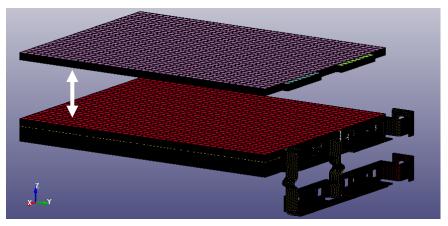
Simulation Mesh



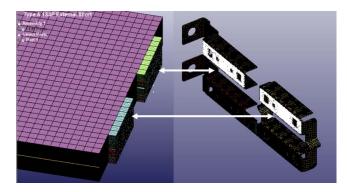
**Current Pathway** 



Cell-to-Cell Heat Transfer



Cell-to-Bus Thermal and Electrical

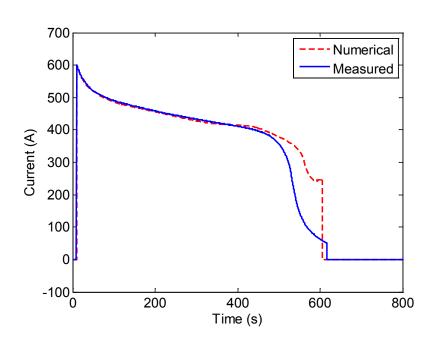


- Leveraging our legacy experiments to confirm model developments prior to full-scale validation
- Simulation set up to match a DOT/NHTSA project Type A 1S4P module external short circuit using newly developed LS-DYNA keywords \*EM\_RANDLE and \*EM\_ISOPOTENTIAL

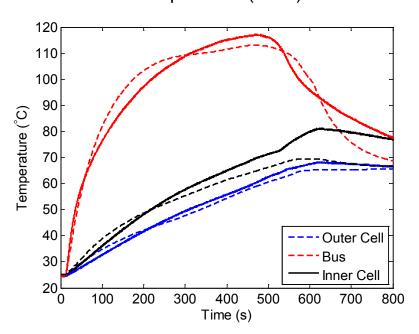
### Technical Accomplishments and Progress: External Short Circuit Validation



#### Model Predicted Current versus Experiment



#### Model Predicted (Dashed) Temperatures versus Experiment (Solid)



- Good agreement between numerical and measured data for electrical variables.
- Thermal predictions demonstrate agreement of 5-10 °C between numerical and experimental data (excluding >550 s for inner cell).

### Technical Accomplishments and Progress: Mechanical and EM Simulation of Module (5P4S)



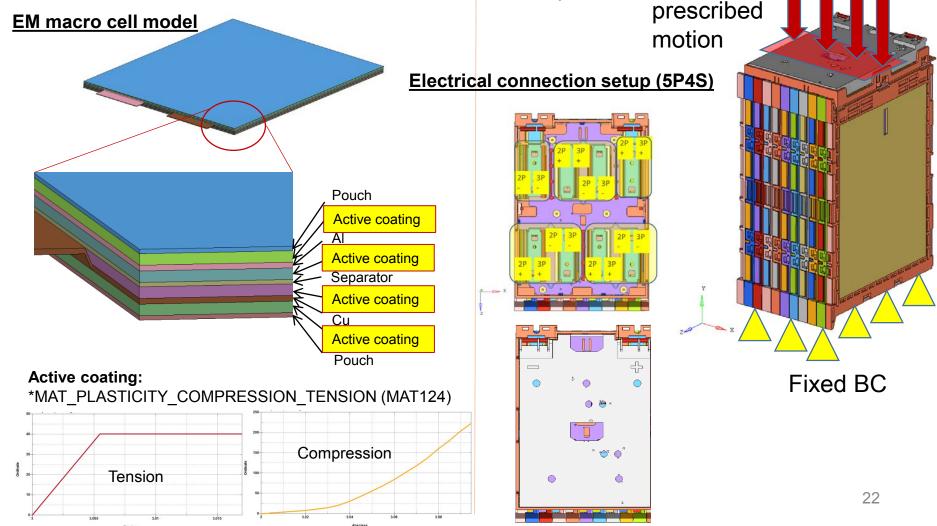
#### Objectives

#### Module crush CAE run setup

nodal

Simulate mechanics to define electrical contact points.

Simulate external short circuit EM and thermal response.

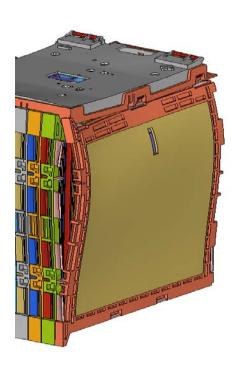


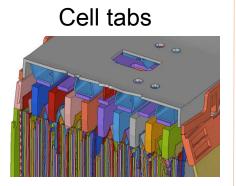
### Technical Accomplishments and Progress: Mechanical and EM Simulation of Module – Crush Results

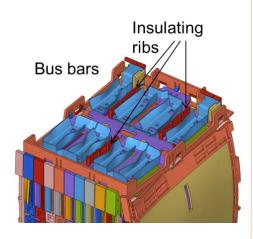
Crush CAE results

#### **Deformation**

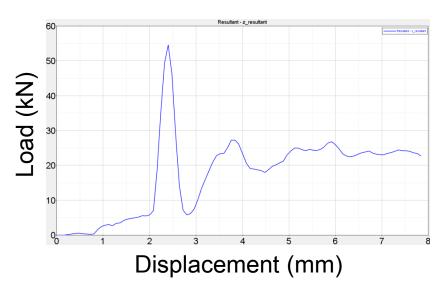
@ 5mm in crush amount







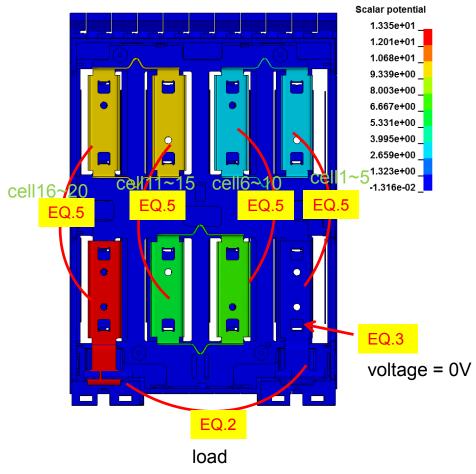
#### Force-displacement



Indenter speed = 1mm/ms

### Implementation of Meshless Randle Circuit for External Shorts 2.5 s Compression Simulation Results

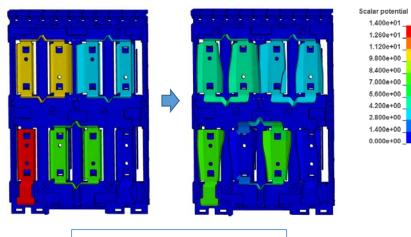
Meshless Randle Circuit
 EM connection types:



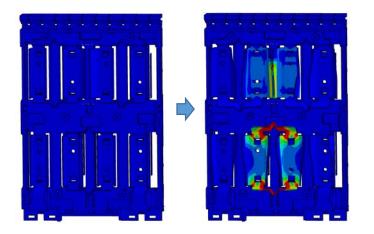
#### **Connection Type:**

EQ2.: Resistance, EQ.3: Voltage Source, EQ.5: Randle Circuit.

**Electrical Potential** 







9.000e+00 \_ 8.000e+00 \_ 7.000e+00 \_ 6.000e+00 \_ 5.000e+00 \_ 4.000e+00 \_ 3.000e+00 \_ 2.000e+00 \_ 1.000e+00 \_

Current density

Electrical potential drop and current density increase shown after external short was captured.





- A reviewer suggested CT scanning method for the microstructure characterization and visualization of the cell component deformations subject to mechanical loads.
  - A more cost effective method to address this request can be the microstructure model developed based on the SEM images of the cell components (i.e. SEM images of a separator under tensile loads).

### Collaboration and Coordination with Other Institutions



- ORNL is developing methods to scale-up detailed mechanical and electrochemical simulations to reduce computational complexity while retaining high fidelity.
  - ORNL also collaborates with Lawrence Berkeley National Laboratory and Sandia National Laboratory under ES295.



 LS-DYNA® is the CAE software of choice for the project and contains key, battery-specific solver enhancements.

### Remaining Challenges and Barriers/ Future Research

- Development of the damage and failure models inside the layered solid element.
- Find optimal mechanical models to get correct cell deformations.
- Define the failure condition that triggers internal short circuit.
- Couple the mechanical deformations with the EM models to define the internal short circuit resistances.
- Model development for the larger scale with multiple cells meeting the targeted computational time and memory.

#### **Proposed Future Research**

- Carry out characterization tests for the input parameters of the Type-E cell for its model development.
- Develop models for internal short configurations based on the damage and failure in the cells.
- Scale the simulation method to enable durability assessment of modules and packs.
- Development of a battery packaging module in LS-PREPOST to help users set up cases.





- Layered solid mechanics are being expanded to incorporate battery constitutive models and failure modes.
- Battery-specific solver developments have been incorporated into battery abuse simulation case studies.
- Module-level multiphysics model of crush-to-external short circuit is under development. LSTC has assisted with the de-bugging process and recent results are promising for delivering multiphysics capability with minimal computational cost.
- Methods to represent component mechanics are under development. An optimization approach is being used to build a mesh that replicates an anisotropic separator response.
- Graphical user interface is progressing according to expectations.
- Validation experiments are fully defined and the associated purchase orders were issued.





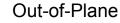
### **Technical Back-Up Slides**

### Development Assumptions



	Crash	Regulatory Crush	Overcharge/External Short/Thermal Ramp
Mechanics Time Scale	< 100 ms	> 10 s	> 10 s
EET Time Scale		ms to minutes	
Deformation Mode	Out-of-Plane or In- Plane Compression; Bending; Shear	Out-of-Plane Compression; In-Plane Compression	Internal Swelling; Separator Melting
Solver Assumption	Explicit to Implicit	Implicit	Implicit

- 3-D, transient finite element code needed to span these target applications
- Methods to span time scales of mechanics and EET will be developed



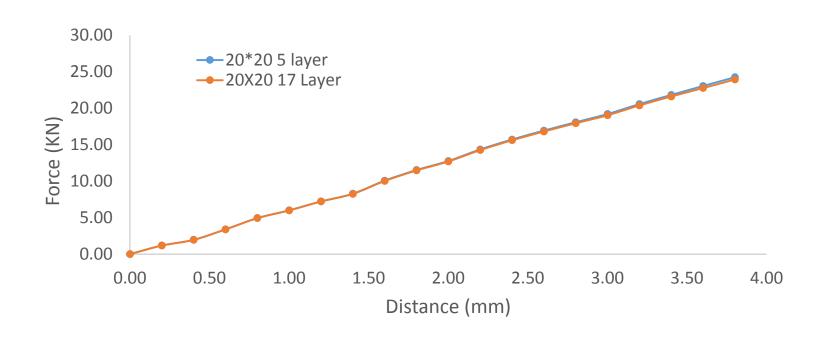


### Hardware Selection



Mesh/Geometry	Туре	Cathode Chemistry and Format	Cell	Module	Pack
Type and construction of the construction of t	A	NMC//LMO Blend Pouch	15 Ah 3.7 V 0.06 kWh	4P1S 5P4S	4S5P (x9) + 2S5P (x2)
Comment of the second of the s	В	NMC Pouch	20 Ah 3.6 V 0.07 kWh	3P1S and 3P10S	
2,3 mm areas and a land	С	LFP Prismatic	18 Ah 3.2 V 0.06 kWh	4P1S 5P2S	36S5P
	D	NMC Pouch	21 Ah 3.65 V	5P4S	4S5P (x9) + 2S5P (x2)
	E	Metal Oxide Blend Prismatic	60 Ah 3.65 V (est)	TBD	
Legacy Hardware Hardware sourced for this project					

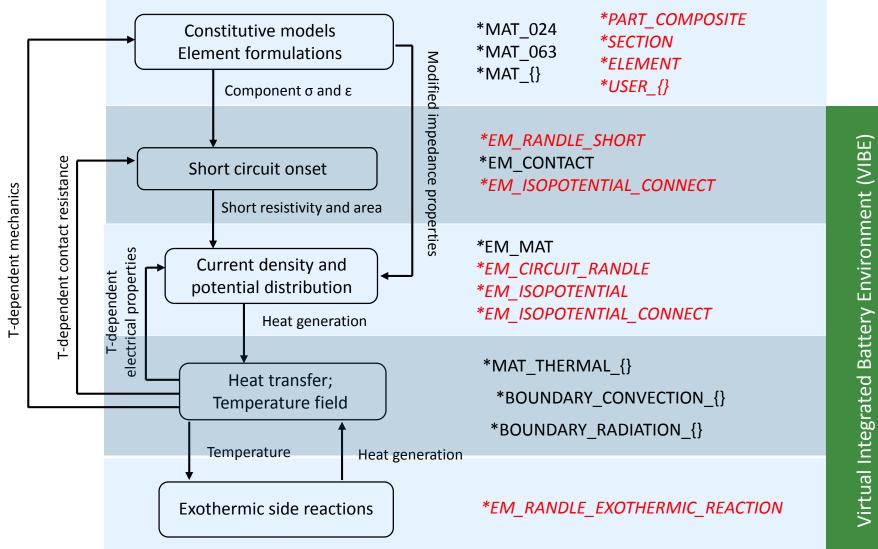
# Layered Solid Model – Element Discretization and Indentation Simulation Comparison



- Computational time 20X40 17 layers = 632 second
- Computational time 20X20 5 layers = 502 second
- Computation time for solid elements = 52705 second
- Computational time savings = 105 times

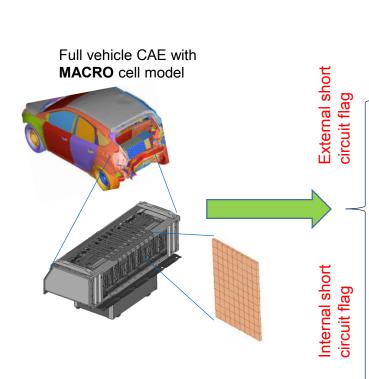
### Combined Solver Development Assumptions for **Crush/External Short Circuit/ Thermal Ramp**



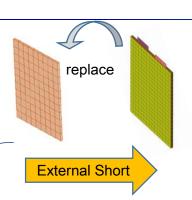


### Roadmap for Macro, EM Macro, and Meso

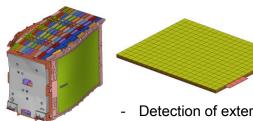




Model	Cell Elements	Explicit time step
Macro	100-300	7E-4 ms
EM macro	600-2.7k	1E-4 ms
Meso	150k-3.8M	1.6E-6 ms



Replace problematic cells with EM Macro cells model

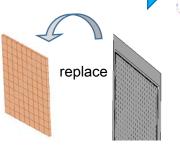


Detection of external contact

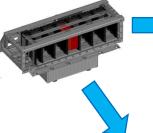
Subsequent EM and thermal evolution due to external contact

Replace problematic cells with MESO cell models

**Internal Short** 



Sub-cycling applied to the meso cells



More accurately identify short circuit using meso cell model failure criteria (smaller safety factor)



Coupled EM/Mechanical response to detect thermal runaway in longer time scale

